ABSTRACT

ELECTRONIC DEVICE WITH HIGH LEAD DENSITY

An electronic device moldable to form a leadless electronic package and a method of forming the electronic device are provided. The electronic device comprises a die pad adapted for attachment of a die and a frame surrounding the die pad. A plurality of leads extend from the frame towards the die pad such that each lead has a bonding site on a top surface thereof configured for attachment of a bonding wire. The said leads include a first set of leads having bonding sites located substantially on a first plane and a second set of leads having bonding sites located substantially on a second plane that is parallel to but spaced from the first plane.

(Figure 8)

162162

G00001